

65 19.55 (New) The composition of claim 27, comprising, relative to the total weight of the composition, less than 10 wt% of N-vinyl functional or vinyl ether functional compounds having a molecular weight below about 500.

REMARKS

Upon entry of this amendment, claims 19, 27, 29, and 31-53 will be pending, of which claims 27 and 49 are independent. Independent claims 27 and 49 have been amended to include that the radiation curable composition, after cure, has a dielectric dissipation factor at 60 Hz and 150°C of lower than about 0.2. In addition, new claims 50-53 have been added to further specify the invention and claim 30 has been cancelled. Support for the above amendments and new claims can be found throughout the application as filed. For instance, support for the amendments to independent claims 27 and 49 amendment can be found on page 2, lines 20-24, of the specification. No new matter has been added. Reconsideration of the outstanding rejections is respectfully requested in view of the above amendments and the following remarks.

Claims 29 and 49 stand rejected under 35 U.S.C. §112, second paragraph. The claims have been reviewed and revised bearing in mind the Examiner's concerns and it is respectfully submitted that all claims, as amended, are in full compliance with 35 U.S.C. §112.

Claims 19, 27, 29-49 stand rejected under 35 U.S.C. § 102 as being obvious over EP 0,081,041 (hereinafter "EP '041"). In addition, claims 19, 27, 29-49 stand rejected under 35 U.S.C. § 103 as obvious over US Patent No. 5,352,712 to Shustack in view of EP '041. Applicants respectfully traverse these rejections for at least the following reasons.

The present invention relates to compositions that, after cure, have a dielectric dissipation factor at 60 Hz and 150°C of lower than about 0.2.

The references cited by the Examiner relate to the field of optical fibers and do not seem to be concerned with carefully selecting the ingredients for their compositions in order to achieve dielectric dissipation factors at 60 Hz and 150°C of lower than about 0.2. Indeed,

Applicants respectfully submit that these references, either alone or in combination, do not provide one of ordinary skill in the art with any teaching on how to prepare compositions having such a low dielectric dissipation factor, and it is respectfully submitted that the present invention is patentable over the cited art.

CONCLUSION

Because all rejections have been addressed and overcome, it is respectfully submitted that the present application is in condition for allowance and a Notice to that effect is earnestly solicited. If any questions remain, the Examiner is encouraged to call the undersigned attorney to expedite the prosecution of this application.

Respectfully submitted,

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